

**Product Code: AN10 AN20 AN60 AN210 AN220 AN260**

## PRODUCT DESCRIPTION

Polyimide film with copper foil on one or both sides, bonded together with a proprietary C-staged modified acrylic adhesive.

### Copper-Clad Product

<b>Copper</b> oz/ft <sup>2</sup> (g/m <sup>2</sup> ) 1 (305)	<b>Adhesive</b> Mil (µm) 1 (25)	<b>Kapton</b> Mil (µm) 1 (25)	<b>IPC</b> Cert.1 Yes
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## Copper-Clad Laminate Properties vs IPC Specifications

Property	IPC Spec	Typical Clad Value
Peel Strength, min., lb/in (kg/cm)		
As received	8 (1.4)	10 (1.8)
After solder	7 (1.3)	9 (1.6)
Dimensional Stability, max., percent	0.15	0.10
Dielectric Constant, max. (at 1 MHz)	4.0	3.6
Dissipation Factor, max. (at 1 MHz)	0.03	0.02
Volume Resistivity, min., megohm-cm (ambient)	10 <sup>7</sup>	10 <sup>9</sup>
Surface Resistivity, min., megohm-cm (ambient)	10 <sup>6</sup>	10 <sup>8</sup>

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